

*** TTL:**

- DTL vs. TTL: 1. TTL less silicon surface than DTL (2 diodes).
- 2. The propagation delay is improved.
- 3. unnecessary to add R_D for charge removing.
- 4. TTL can be designed as Tristate logic gate.

• Comparison (DTL & TTL): $I_{RD} = \frac{V_{BE(sat)}}{R_D}$, $|I_{B,ol}| = \frac{V_{CC} - V_{CE(sat)} - V_{BE(FA)}}{R_B}$, factor of improvement = $\frac{|I_{B,ol}|}{|I_{RD}|}$

• Basic TTL:

Temp. 74x100 \rightarrow (0~70°C)
54x100 \rightarrow (-55~125°C)

states

	V_{OH}	V_{OL}
Q_I	SAT.	R.A.
Q_O	OFF.	SAT.

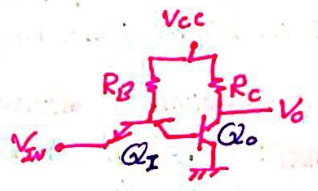
• VTC:

$$V_{OH} = V_{CC}$$

$$V_{OL} = V_{CE(sat)}$$

$$V_{IL} = V_{BE(FA)} - V_{CE(sat)}$$

$$V_{IH} = V_{BE(sat)} - V_{CE(sat)}$$



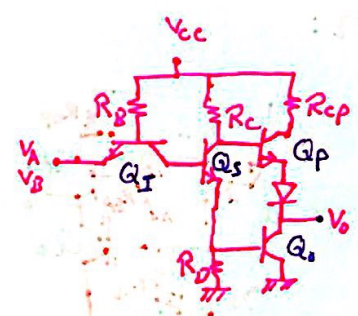
• TTL with Totem Pole:
"3-Break Points"

* Purpose of each element:

- Q_I \rightarrow shifting of transition, pull down of Q_S
- R_B \rightarrow Limits I_{IL}
- D_L \rightarrow level shifting between V_{CC} & output.

states

	Zero	V_{OH}	V_B	V_{OL}
Q_I	SAT	SAT	SAT	R.A.
Q_S	OFF	F.A.	F.A.	SAT
Q_P	OFF	OFF	F.A.	SAT
Q_O	F.A.	F.A.	F.A.	OFF
D_L	-	E.O.C.	E.O.C.	OFF



- Q_S \rightarrow provide base driving current to Q_O , B-E level shifting for shift of transition width, pull down of Q_P .
- Diodes \rightarrow To limit -ve swing of the inputs to one diode drop below ground.

- $D_{CA,B}$
- R_C \rightarrow provide logic inversion to OH driver. Q_O \rightarrow OL driver for current sourcing pull down.
- R_D \rightarrow Discharge path for Saturation stored charge of Q_O . Q_P \rightarrow Provide Active current sourcing pull up.
- R_{CP} \rightarrow Part of active pull-up, limits current spike during OH to OL transition.

* FAN-OUT:

$$I_{IL} = \frac{V_{CC} - V_{BE(sat)} - V_{CE(sat)}}{R_B} \dots (1)$$

$$I_{RD} = \frac{V_{BE(sat)}}{R_D} \dots (2)$$

$$I_{C,S} = I_{R_C} = \frac{V_{CC} - V_{CE(sat)} - V_{BE(sat)}}{R_C} \dots (3)$$

$$I_{B,S,I} = \frac{V_{CC} - V_{BC(R.A)} - V_{BE(sat)} - V_{BE(sat)}}{R_B} \dots (4)$$

$$I_{B,S} = -(1+\beta_R) I_{B,I} \dots (5)$$

$$I_{E,S} = |I_{B,S}| + I_{C,S} \dots (6)$$

$$I_{B,O} = I_{E,S} - I_{RD} \dots (7)$$

$$I_{OL} = \beta_F \sigma I_{B,O} \dots (8)$$

$$N = \frac{I_{OL}}{I_{IL}} \dots (9)$$

$$V_{OH} = V_{CC} - V_{BE(ON)} - V_D(ON)$$

$$V_{OL} = V_{CE(SAT)}$$

$$V_{IL} = V_{BE(FA)} - V_{CE(SAT)}$$

$$V_{IH} = V_{BE(SAT)} + V_{BE(SAT)} - V_{CE(SAT)}$$

$$V_{IB} = V_{BE(FA)} + V_{BE(FA)} - V_{CE(SAT)}$$

$$V_{OB} = V_{CC} - I_{R_C} R_C - V_{BE(FA)} - V_{D_L(ON)}$$

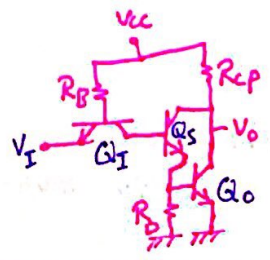
$$I_{R_C} \approx I_{R_D} = \frac{V_{BE(FA)}}{R_D}$$

• Power Dissipation:

$$I_{CC(OL)} = (3) + (4) \Rightarrow P_{diss} = \frac{I(OH) + I(OL)}{2} \cdot V_{CC}$$

$$I_{CC(OH)} = \frac{V_{CC} - V_{BE(SAT)}}{R_B}$$

*** Special TTL:**



→ Power diss.:

$$I_{OL} = \frac{V_{CC} - V_{CE(sat)}}{R_{cp}} + \frac{V_{CC} - V_{CE(RA)} - V_{BE(sat)} - V_{BE(sat)}}{R_B}$$

$$I_{OH} = \frac{V_{CC} - V_{BE(sat)} - V_{CE(sat)}}{R_B}$$

$$P_{diss} = \frac{I_{OH} + I_{OL}}{2} \cdot V_{CC}$$

*** STTL:**

Resistors ↑ ⇒ I ↓, N ↓, P ↓, propagation delay ↑

- Main advantage of STTL: Improve Transient Times.
- SBJT vs. BJT: Base Region metal contact is Extended to overlap part of the collector N-region.

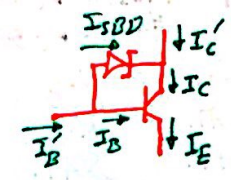
*** Mode of Operations:**

*** Forward:** $V_{BE(F.A)} = 0.7V$

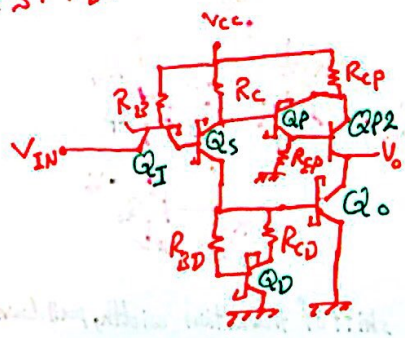
*** ON HARD:** $V_{BE} = 0.8V$
 $V_{CE} = 0.5V$
 $V_{BC} = 0.3V$

⇒ Total $I_c' = \beta I_B + I_{SBD}$
 $I_c(HARD) = \beta_F I_B$

*** Reverse Mode:**
 $I_B' = -I_c' = I_{SBD}$
 $V_{BC(R.S)} = 0.3V$
 $I_E = 0$



*** STTL:**



→ Narrower transition width & improved Noise Margins which achieved using QD.

*** VTC:**

$$V_{OH} = V_{CC}$$

$$V_{OL} = V_{CE(ON\ HARD)}$$

$$\text{Logic Swing} = V_{OH} - V_{OL}$$

Notes:

	Q1	Qs	Qp	Qp2	QD	Qo
V _{OH}	HARD	OFF	EOC	EOC	OFF	OFF
V _{OL}	R.A	HARD	F.A	OFF	HARD	HARD

• Prove that Qp always ON in both cases:

- V_{OH}: since Q_s OFF, V_{cc} applied to base of Q_p through R_{EP}.
- V_{OL}: V_B = V_{BE(HARD)} + V_{CE(HARD)} = 1.3 volt which will turn on Q_p since it is grounded through R_{EP}.

*** VTC:**

$$V_{OH} = V_{CC} - V_{BE,p(F.A)} - V_{BE,p2(F.A)}$$

$$V_{OL} = V_{CE,o(HARD)}$$

$$V_{L} = V_{BE,o(F.A)} + V_{BE,s(F.A)} - V_{CE,s(HARD)}$$

$$V_{IH} = \frac{V_{BE(HARD)} + V_{BE(HARD)} - V_{CE,s(HARD)}}{2}$$

*** FAN-OUT:**

$$I_{IL} = \frac{V_{CC} - V_{BE(HARD)} - V_{CE(HARD)}}{R_B} \dots (1)$$

$$I_{CSD} = \frac{V_{BE(HARD)} - V_{CE(HARD)}}{R_{CSD}} \dots (2)$$

$$I_{RC} = \frac{V_{CC} - V_{CE(HARD)} - V_{BE(HARD)}}{R_C} \dots (3)$$

$$I_{RB} = I_{SBD} = \frac{V_{CC} - V_{BE(R.S)} - V_{BE(HARD)} - V_{BE(HARD)}}{R_B} \dots (4)$$

$$I_{ES} = I_{RB} + I_{RC} \dots (5)$$

$$I_{B,o} = I_{ES} - I_{CSD} \dots (6)$$

$$I_{OL} = \beta_F I_{B,o} \dots (7)$$

$$N = \frac{I_{OL}}{I_{IL}} \dots (8)$$

*** Power Diss.:**

$$I_{OL} = I_{RC} + I_{E,p} + I_{RB} \dots (4)$$

$$I_{OH} = I_{RB} + I_{E,p}$$

same (3) replace R_c by R_B

$$I_{E,p} = \frac{V_{CC} - V_{BE(F.A)}}{R_{EP}} \Rightarrow P_{diss} \checkmark$$

$$I_{E,p} = \frac{V_{BE(HARD)} + V_{CE(HARD)} - V_{BE(F.A)}}{R_{EP}}$$

*** LSTTL:**

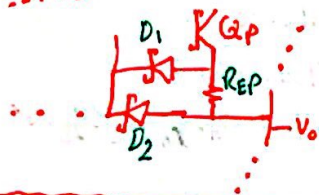
- Replace Q_s By 2 shottky diodes:
- Reduce the input Capacitance.

*** VTC:**

$$V_{OH} = V_{CC} - V_{BE(F.A)}$$

$$V_{L} \& V_{IH} \text{ reduced by } 0.2 \text{ Volt.}$$

STTL:



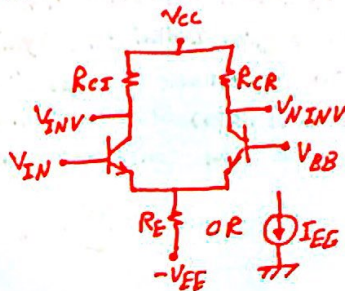
- Connecting R_{EP} with Q_p : allows Q_p to begin charging the load capacitance before Q_n is ON, so it seeds up the L-to-H transition switching.
- D_1 & D_2 used near the darlington: for enhance the transient properties.

ECL

- Advantages of ECL: 1) No need for pull up & pull down since it doesn't saturate. 2) Improve FANOUT. 3) Fast Switching Time. 4) Eliminate current spikes (Low Noise).

• Smaller logic swing gives: Constant Current Source & Avoidance of a totem-pole-output.

states	input	input state	Inv. op state	NINV op state
	$V_{IN} < V_{BB}$	Low	High	Low
	$V_{IN} > V_{BB}$	High	Low	High



* Typical Values:

- Propagation Delay = 1ns.
- $P_{diss} = 25mW$.

VTC:

$$V_{OH} = V_{CC}$$

$$V_{IL} = V_{BB} - 0.05$$

$$V_{IH} = V_{BB} + 0.05$$

$$V_S = \frac{V_{CC} + V_{BE}(sat) + \frac{R_{C1}}{R_E} [V_{BE}(sat) - V_{EE}]}{1 + \frac{R_{C1}}{R_E}}$$

$$V_{OL} = V_{CC} - \frac{R_{C1}}{R_E} [V_{IH} - V_{BE}(ECL) + V_{EE}]$$

Analysis:

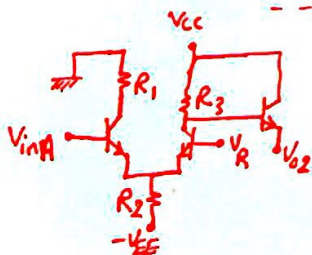
• Case (I): $V_I = V_{BB}$: [Q_1 & Q_2 F.A.] $\Rightarrow I_E = \frac{V_E + V_{EE}}{R_E}$; $V_E = V_{BB} - V_{BE}(FA)$ for identical Q_1 & Q_2 : $I_{E1} = I_{E2} = 0.5 I_E$.

• Case (II): $V_I < V_{BB}$: [Q_1 OFF] \rightarrow since $V_{DE} = 1.8 - 2 + 0.75 = 0.55 < 0.75$ "OFF"

$$V_{BE2I} = V_{IN} - V_{BB} + V_{BE}(ECL); V_{NINV} = V_{CC} - I_C R_C; I_{C1} \approx I_{E2} = \frac{V_I - V_{BE2I}(ECL) + V_{EE}}{R_E}$$

• Case (III): $I_E = \frac{V_{BB} - V_{BE}(ECL) + V_{EE}}{2R_E} \rightarrow V_O = V_{CC} - I_E R_C$

• Case (IV): [Q_1 SAT] $I_E(sat) = \frac{V_S - V_{BE}(sat) + V_{EE}}{R_E}$; $V_{INV} = V_{CE}(sat) + \frac{I_E(sat)}{(\beta+1)} R_E + V_{EE}$.



V_{IL} & V_{IH} givens:

V_{OL} @ V_{IL} :

$$V_{OH} @ V_{IH}: V_{OH} = V_{CC} - I_{R3} R_3 - V_{BE}(ECL)$$

$$I_{R3} \approx 0 \Rightarrow V_{OH} = V_{CC} - V_{BE}(ECL)$$

$$V_{OL} = V_{CC} - I_{R3} R_3 - V_{BE}(ECL)$$

$$I_{R3} \approx I_{R2} = \frac{V_R - V_{BE}(ECL) + V_{EE}}{R_2}$$

$$V_{IH} = V_R + 0.05$$

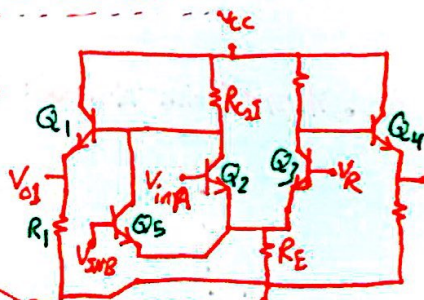
$$V_{IL} = V_R - 0.05$$

V_S same previous relation

$$V_{OL} = -V_{BE}(ECL) - \frac{R_{C1}}{R_E} [V_{IH} - V_{BE}(ECL) + V_{EE}]$$

$$V_{OH} = V_{CC} - I_{B3Q1} R_{E3I} - V_{BE3Q1}(ECL)$$

$$I_{B3Q1} = \frac{V_{EE} - V_{BE3Q1}(ECL)}{R_{C1} + (\beta+1)R_1}$$



TRUE information:

- A smaller input capacitance will speed down the switching time of load gates. x
- A smaller o/p R will provide a smaller charging current for C_L & faster switching time. x
- In order that H-L voltage levels always be distinguishable, we must always have $V_{OH} > V_{IH}$ & $V_{OL} < V_{IL}$. ✓
- For VTC, we try our best to get the LS. as small as possible. x
- FAN out more important than FAN in. ✓
- Max fanout of digital logic cct is restricted by its V_{IH} & V_{OL} . x
- Max. Fanout is limited by OL state of driving gate. x
- For inverter, L-to-H prop. delay time refers to: High to low transition of the input. ✓
- For PN diode @ given current, the required forward-bias voltage ↓ when T ↑. ✓
- PN junction Capacitance C_j helps V_j to change instantaneously. x
- Cap. of Varicap is inversely proportional to the square root of the V applied to the diode. ✓
- Using DRL, we can construct NAND & NOR gates. x

MOSFET:

$K_n = \frac{K'}{2} \cdot \frac{W}{L}$, $K' = \mu C_{ox}$, $C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$

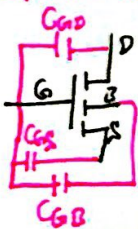
$\mu_n (Si) = 580 \frac{cm}{V \cdot s}$
 $\mu_p (Si) = 230 \frac{cm}{V \cdot s}$

Mode of operation:

NMOS: $V_{GS} > V_{TN}$ → if YES "ON" $V_{DS} > V_{GS} - V_{TN}$ → if YES "SAT", $I_D(sat) = \frac{K_n}{2} [V_{GS} - V_{TN}]^2$
 → if NO "OFF", $I_D = 0$ → if NO "LIN", $I_D(lin) = K_n [(V_{GS} - V_{TN}) V_{DS} - \frac{V_{DS}^2}{2}]$

PMOS: $V_{SG} > -V_{TP}$ → if YES "ON" $V_{SD} > V_{SG} + V_{TP}$ → if YES "SAT", $I_D(sat) = \frac{K_p}{2} [V_{SG} + V_{TP}]^2$
 → if NO "OFF", $I_D = 0$ → if NO "LIN", $I_D(lin) = K_p [(V_{SG} + V_{TP}) V_{SD} - \frac{V_{SD}^2}{2}]$

Capacitances of MOSFET:

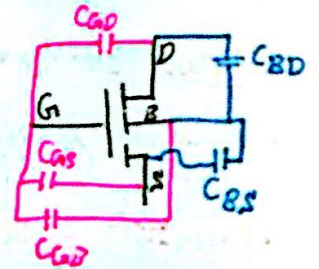


*** Gate Oxide Capacitances:**

$C_G = C_{GD} + C_{GS} + C_{GB}$
 $C_{GB} = WL C_{ox}'$
 $C_{ox}' = \frac{\epsilon_{ox}}{t_{ox}}$

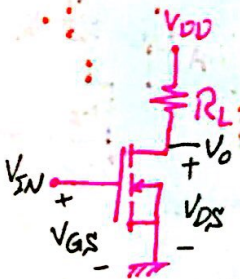
*** Junction Capacitances:**

$C_{BS}(V_{BS}) = \frac{C_{BS0}}{[1 - \frac{V_{BS}}{\phi_{BS}}]^{MB}}$
 $MB \equiv$ Grading Factor ($\frac{1}{2}$ or $\frac{1}{3}$)
 $\phi_{BS} \in [0.9 - 1]$ Volt.



$C_G \gg C_J$

MOSFET with R-load:



$V_{TN} = 0.2 * V_{DD}$

@ Break Points: $\frac{\partial V_0}{\partial V_I} = -1$

VTC:

$V_{OH} = V_{DD}$
 $V_{OL} = \frac{V_{DD}}{K R_L (V_{DD} - V_T) + 1}$
 $V_{IL} = V_T + \frac{1}{R_L K}$
 $V_m: \frac{K}{2} V_m^2 + [\frac{1}{R_L} - K V_T] V_m + [\frac{K}{2} V_T^2 - \frac{V_{DD}}{R_L}] = 0$
 $V_{IH}: \frac{3}{8} K (V_{IH} - V_T)^2 + \frac{1}{2 R_L} (V_{IH} - V_T) - \frac{V_{DD}}{R_L} = 0$

5

Power Dissipation: $P_{dynamic} = N C_L V V_{DD}^2$ (Number of gates)
 $P_{static} = \frac{I_{OH} + I_{OL}}{2} \cdot V_{DD}$ (freq.)
 Dynamic power \equiv Transient Power.
 $\Rightarrow P_{Total} = P_{static} + P_{dyn.}$

\Rightarrow for MOSFET with R_L : $I_{OH} = 0$, $I_{OL} = I_D(Lin) = K_n [(V_{GS} - V_T) V_{DS} - \frac{V_{DS}^2}{2}]$

$P_{DD}^{(avg)} = P_{static} = \frac{1}{2} V_{DD} I_D(Lin)$

* Rise & Fall Time:

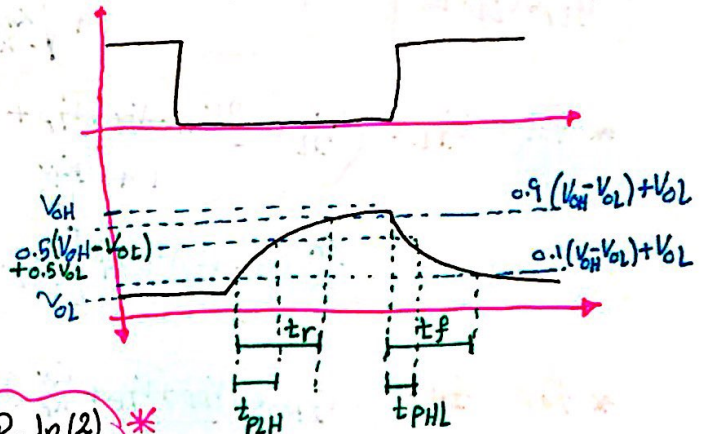
\rightarrow Rise time:

$t_r \rightarrow V_1: 10\%$, $V_2: 90\%$
 $t_{PLH} \rightarrow V_1: 10\%$, $V_2: 50\%$
 $\Delta t = C_L R_L \ln \left[\frac{V_{DD} - V_1}{V_{DD} - V_2} \right]$

for t_r : $V_1 = V_{OL} + 0.1(V_{OH} - V_{OL})$
 $V_2 = V_{OL} + 0.9(V_{OH} - V_{OL})$

$\Rightarrow t_r = 2.2 C_L R_L$ *

for t_{PLH} : $V_1 = V_{OL} + 0.1(V_{OH} - V_{OL})$, $V_2 = V_{OL} + 0.5(V_{OH} - V_{OL})$
 $\Rightarrow t_{PLH} \approx C_L R_L \ln(2)$ *



\rightarrow Fall Time:

* $t_f = \frac{C_L}{K} \left[\frac{2(V_T + 0.1V_{OL} - 0.1V_{DD})}{(V_{DD} - V_T)^2} \right] + \frac{1}{V_{DD} + V_T} \ln \left[\frac{1.9V_{DD} - 2V_T - 0.9V_{OL}}{0.1V_{DD} + 0.9V_{OL}} \right]$ *
 $t_{PHL} = \frac{2C_L V_T}{K(V_{DD} - V_T)^2} + \frac{C_L}{K(V_{DD} - V_T)} \ln \left[\frac{1.5V_{DD} - 2V_T - 0.5V_{OL}}{0.5V_{DD} - 0.5V_{OL}} \right]$ *

* TTL (open Collector Gate):

- TTL without Totem Pole.
- Output stage doesn't have active Pull-up Transistor.
- A need to active pull-up R (typically $10K\Omega$) \rightarrow it is used to change the magnitude of the load current.

\Rightarrow Advantage:

outputs of different gate can be wired together resulting in ANDing of their outputs.

CMOS:

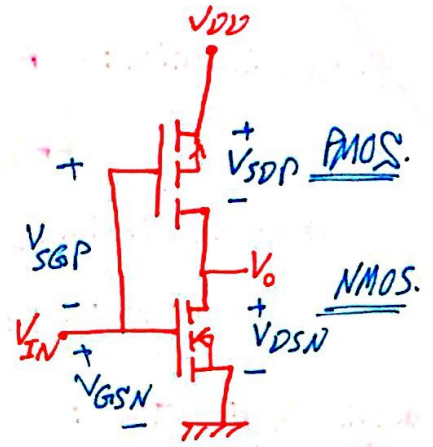
VTC:

$V_{OH} = V_{DD}$, $V_{OL} = \text{Zero}$

$V_{GS} = V_{IN}$
 $V_{SGP} = V_{DD} - V_{IN}$
 $V_{DSN} = V_o$
 $V_{SDP} = V_{DD} - V_o$

* Mid Point voltage:

$V_m = \frac{V_{DD} + V_{TP} + \sqrt{\frac{K_n}{K_p}} V_{TN}}{1 + \sqrt{\frac{K_n}{K_p}}}$



* for V_{IL} :

$V_{IL} = \frac{2V_{out} - V_{DD} + V_{TP} + \frac{K_n}{K_p} V_{TN}}{1 + \frac{K_n}{K_p}} \dots (1)$

$\frac{K_n}{2} (V_{IL} - V_{TN})^2 = K_p \left[(V_{DD} - V_{IL} + V_{TP})(V_{DD} - V_{out}) - \frac{(V_{DD} - V_{out})^2}{2} \right] \dots (2)$

* for V_{IH} :

$V_{IH} = \frac{V_{DD} + V_{TP} + \frac{K_n}{K_p} (V_{TN} + 2V_{out})}{1 + \frac{K_n}{K_p}} \dots (1)$

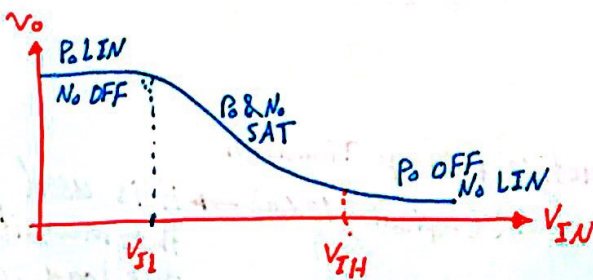
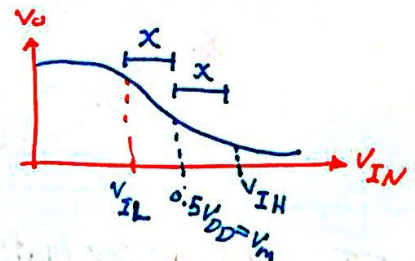
$K_n \left[(V_{IH} - V_{TN}) V_{out} - \frac{V_{out}^2}{2} \right] = \frac{K_p}{2} (V_{DD} - V_{IH} + V_{TP})^2 \dots (2)$

** Symmetric CMOS Inverter:

Best Value: $V_m = 0.5V_{DD}$

$\rightarrow K_n = K_p$
 $V_{TN} = |V_{TP}|$

\rightarrow find $V_{IL} \Rightarrow V_{IH} = 0.5V_{DD} + (0.5V_{DD} - V_{IL})$



• CMOS FAN-OUT:

$C_{LX} = \frac{t_p(\max)}{\frac{2V_{Tx}}{K_x (V_{DD} - V_{Tx})^2} + \frac{1}{K_x (V_{DD} - V_{Tx})} \ln \left[\frac{1.5V_{DD} - 2V_{Tx}}{0.5V_{DD}} \right]}$

solve for:

\rightarrow x is N: $V_{Tx} = +V_{TN}$
 $K_x = +K_{pL}$
 \rightarrow x is P: $V_{Tx} = -V_{TP}$
 $K_p = +K_p$

we find C_{LN} & $C_{LP} = ?!$

\Rightarrow Maximum size of the load inverter:

$C_L = C_{ox} (W_n' L_n' + W_p' L_p')$

$t_r, t_f, t_{PHL}, t_{PLH}$ for CMOS:

$$t_f = \frac{C_L}{W_N/L_N} \left[\frac{2(V_{TN} - 0.1V_{DD})}{K'_N (V_{DD} - V_{TN})^2} + \frac{1}{K'_N (V_{DD} - V_{TN})} \ln \left(\frac{1.9V_{DD} - 2V_{TN}}{0.1V_{DD}} \right) \right]$$

$$t_{PHL} = \frac{2C_L V_{TN}}{K_N (V_{DD} - V_{TN})^2} + \frac{C_L}{K_N (V_{DD} - V_{TN})} \ln \left[\frac{1.5V_{DD} - 2V_{TN}}{0.5V_{DD}} \right]$$

$$t_r = \frac{-2C_L (V_{TP} + 0.1V_{DD})}{K_P (V_{DD} + V_{TP})^2} + \frac{C_L}{K_P (V_{DD} + V_{TP})} \ln \left[\frac{1.9V_{DD} + 2V_{TP}}{0.1V_{DD}} \right]$$

$$t_{PLH} = \frac{-2C_L V_{TP}}{K_P (V_{DD} + V_{TP})^2} + \frac{C_L}{K_P (V_{DD} + V_{TP})} \ln \left[\frac{1.5V_{DD} + 2V_{TP}}{0.5V_{DD}} \right]$$

Design: (sym. CMOS)

$$\frac{W_P}{L_P} = 2.5 \frac{W_N}{L_N}$$

⇒ in Design: Need to know other quantities if not given go to next design.

- find W_P or W_N or missing parameter.
- find K_N & K_P .
- find V_m $V_m = V_{DD}/2$.
- find V_{SL} using previous equation.
- find V_{IH} .
- $C_{ox}^{(NMOS)} = \frac{K'_N}{\mu_n} = C_{ox}^{(PMOS)} = \frac{K'_P}{\mu_p}$

$$\begin{matrix} V_{LS} = V_{OH} - V_{OL} \\ V_{TN} = V_{SH} - V_{IL} \end{matrix}$$

$$\begin{matrix} V_{NAH} = V_{OH} - V_{IH} \\ V_{NML} = V_{IL} - V_{OL} \end{matrix}$$

* Minimum Size CMOS:

"Non-symmetrical"
 $W_N = W_P$ & $L_N = L_P$

$$\frac{W_N}{L_N} = \frac{W_P}{L_P}$$

$$C_{ox} = \frac{3.45 \times 10^{-11}}{t_{ox}}$$

in sym. CMOS.

* Input & Output Capacitances:

$$\begin{matrix} C_{in} = C_{ox} (W_N L_N + W_P L_P) \\ C_{out} = (C_{DN} + C_{DP}) + (C_{GP} + C_{GP}) \end{matrix}$$

* Fan Out:

$$F = \frac{0.058 \mu_n t_p(\text{Max})}{3.5 L^2 \left[\frac{2V_{TN}}{(V_{DD} - V_{TN})^2} + \frac{1}{V_{DD} - V_{TN}} \ln \left(\frac{1.5V_{DD} - 2V_{TN}}{0.5V_{DD}} \right) \right]}$$

* Design CMOS sym. with L_{min} :

• find K_n :
$$K_n = \frac{C_L}{t_{PHL}} \left[\frac{2V_{TN}}{(V_{DD} - V_{TN})^2} + \frac{1}{(V_{DD} - V_{TN})} \ln \left(\frac{1.5V_{DD} - 2V_{TN}}{0.5V_{DD}} \right) \right]$$

• find C_L @ first if not given ($C_L = C_{in}$).

• $W_N = L_{min} \frac{K_N}{K'_N}$

• $W_P = W_N \frac{K_N}{K'_P}$

then write $\frac{W_P}{L_P}$ & $\frac{W_N}{L_N}$

⇒ you could find new C_{in} .

- * To use a common-emitter circuit as an inverter, the output is taken from: Collector.
- * Which of the following is Not a common logic family used today: RTL.
- * The abbreviation TTL means: Transistor-Transistor-logic.
- * One advantage that Mosfet transistors have over bipolar transistor is: High input impedance.
- * The original CMOS Line of ccts is the: 4000 series.
- * Which specialized device distinguishes the 74LSxx ccts from standard 74xx cct is: Schottky diode.
- * A family Logic devices designed from extremely high speed is: ECL.
- * The input transistor on a TTL cct is unusual in that it has: multiple emitters.
- * The 54XX TTL IC series is the military version & has: wider temp. range.
- * The Output current capability for a High output condition is called: Source current.
- * The abbreviated designation for input current with high inputs: I_{IH} .
- * Fan-out for a typical TTL gate is 10.
- * The noise margin for standard TTL gate is: 0.4 Volt.
- * The output current for a low output is called a: sink current.
- * The minimum input voltage recognized as a high by TTL gate is: 2.0 V.
- * " Maximum " " " " a low " " " " : 0.8 V.
- * " " output " " " " " " " " " : 0.4 V.
- * Which of the following is OH valid in TTL: 5.1, 3, 2.6 \Rightarrow All of them.
- * " " " " " OL " " " " : 0.2, 0.3, 0.5 \Rightarrow All of them.
- * An n-ch. DMOS with +ve V_{GS} is operating in which mode: enhancement.
- * True Statement: A DMOS has a physical ch. & can be operated in enhancement mode or depletion mode. * The major advantage of ECL: Very High speed.
- * In Cutoff V_{GS} is equal to: V_{CC} * TTL high level is higher than the low level sinking: FALSE.
- * The shortest propagation delay: ECL.
- * An atom consists of: protons, electrons, neutrons.
- * Nucleus is: protons & Neutrons.
- * Atomic # of silicon: 14.
- * " " " germ.: 32.
- * To saturate BJT: $I_B > I_C(\text{sat})/\beta_{dc}$.
- * PNP, the pregion are: E & C.
- * When operated cutoff & sat, transistor acts like: switch.

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